“A Proposed Junction-Box Stress Test (Using an Added Weight) for Use During the Module Qualification”

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2012/2/29, 8:20 – 8:40 am (Wednesday)

Golden Ballroom

-this presentation contains no proprietary information-

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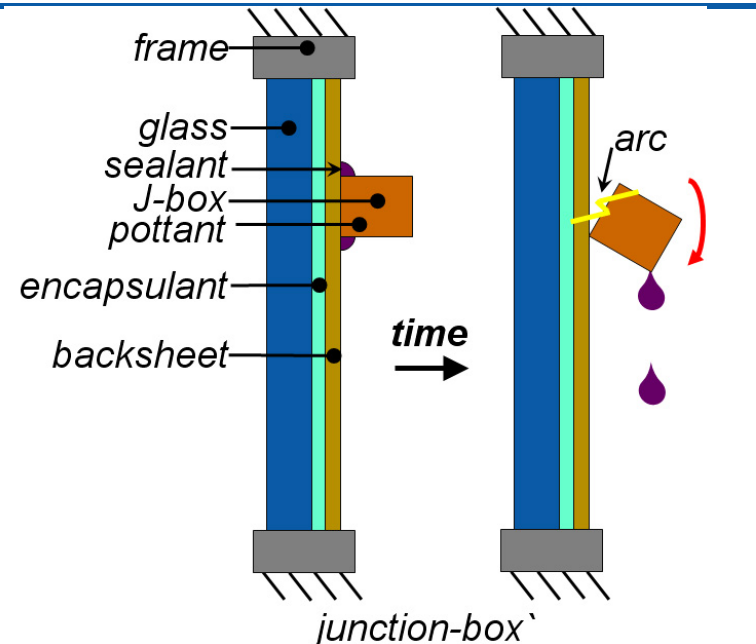
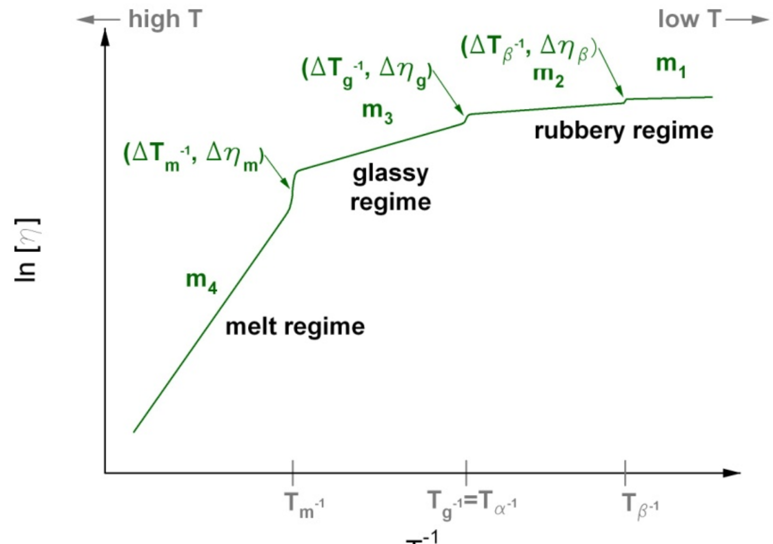
Motivation for the Project

- J-box attachment often proves a milestone to module manufactures … possible consequences of field failure
- Possible failure mechanisms: phase transformation, creep, *cohesive failure*, **delamination** of the -adhesive system-
- Present qual. test: "robustness of termination" (pull ⊥ against j-box 40 N load) after [UV preconditioning, thermal cycling, humidity-freeze], and at room temperature
- Discovery experiments suggest that problematic systems can be more readily identified with applied weight during damp heat



possible field failure mode(s) at the junction-box

D.C. Miller et. al., Proc. IEEE PVSC, 2010, 262-268.



viscosity (flow rate) vs. 1/T for thermoplastic polymer

(Temperature) Conditions Present in the Field

- The cell (module) temperature can be predicted from popular models (King, Faiman, etc.)

  D.L. King et. al., SAND2004-3535 2004; 1-43.
  D. Faiman D, Prog. Photovolt: Res. Appl. 2008; 16: 307–315.

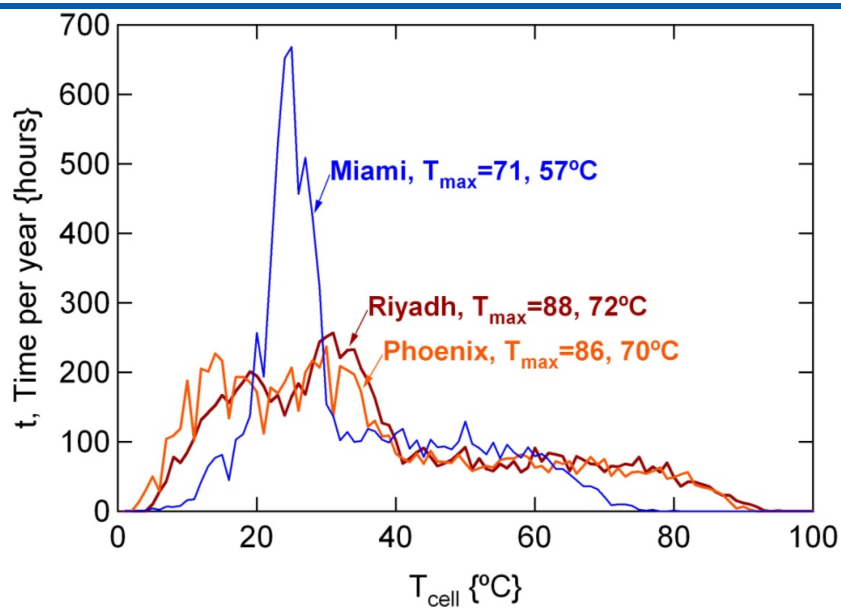
- T_{max} of 105°C achievable for open circuited, roof-mounted modules in desert location

- A greater T_{max} may be realized during the reverse bias condition induced by partial shading, current mismatch, cell or interconnect failure

- Localized $T_{max} \geq 150$°C achievable during the "hot-spot" condition

  E. Molenbroek et. al., Proc. IEEE PVSC 1991; 547-552.
  Oh and TamizhMani, Proc. IEEE PVSC, 2010; 984 – 988.

- Other factors (*e.g.*, moisture) are also present in the field



Time-temperature histories for the cell in roof-mounted modules for a typical year. T_{max} given for roof and rack-mounted modules.

LOCATION	T_{max}, ROOF {°C}	T_{max}, RACK {°C}	$T_{max, record}$, AMBIENT {°C}
Death Valley, CA	108	90	57
Riyadh	103	84	48
Phoenix, AZ	103	85	50
Yuma, AZ	100	83	51
New Delhi	97	79	45
Seville	97	79	45
Kuwait City	99	83	51
Daytona, FL	90	73	39
Denver, CO	89	72	40
Miami, FL	86	70	37
Bangkok	85	69	38
New York, NY	89	73	41
Munich	79	64	36
Fairbanks, AK	70	59	36

*T_{max} predicted from 30 year **record** temperature data*
D.C. Miller et. al., Proc. IEEE PVSC, 2010, 262-268.

Summary of Experiments

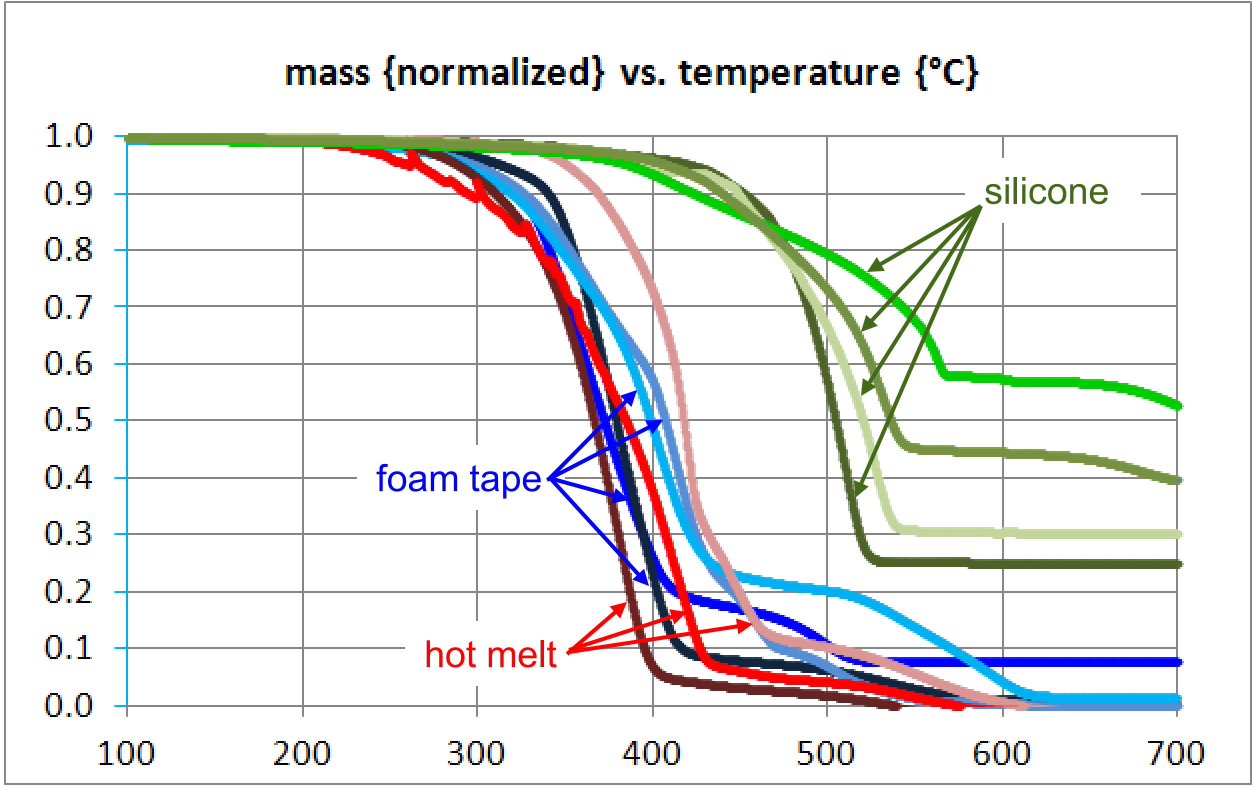
- Specimens:
  - foam tapes (closed cell: acrylic, polyurethane, polyethylene)
  - silicones (condensation cure: acetoxy, oxime, alkoxy cure)
  - hot melt (thermoplastics: EVA, polyolefin, polyamide)

- Material-level tests:
  - thermogravimetric analysis (TGA)
  - differential scanning calorimetry (DSC)
  - dynamic mechanical analysis (DMA)

- Component-level tests:
  - indoor chamber: 1000 hours @ 85°C, 85% RH
  - polyester (PET) “substrate”
  - glass “substrate”

The Decomposition Temperature: Measured vs. Required

- To ensure long term durability in the event of a prolonged hot spot condition:
  - $T_{5\%} > 200°C$ (approximation for test @ $20°C \cdot min^{-1}$)
  - → Examining the event of prolonged hot-spot condition ~ 150°C
  - → $T_{5\%}$ could occur on the order of 50°C lower at slower test rate
- No overt failures relative to this criteria
- Only PU tape, alkoxy silicone, and EVA hot melt approach this criteria: evaluate at slower test rate to verify



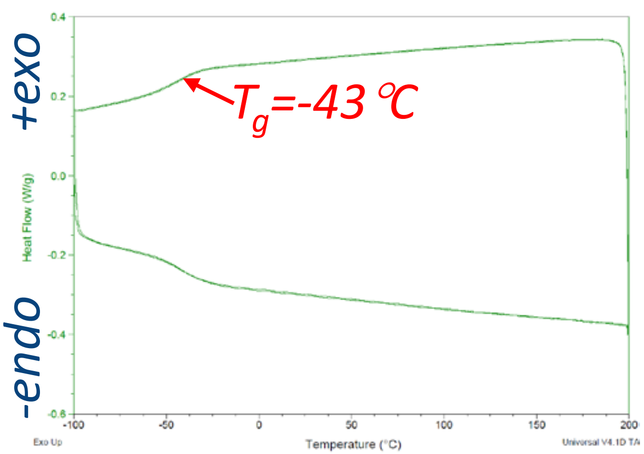
TGA characterization of silicones, foam tapes, and hot melts

DSC Identifies the Likelihood of Creep

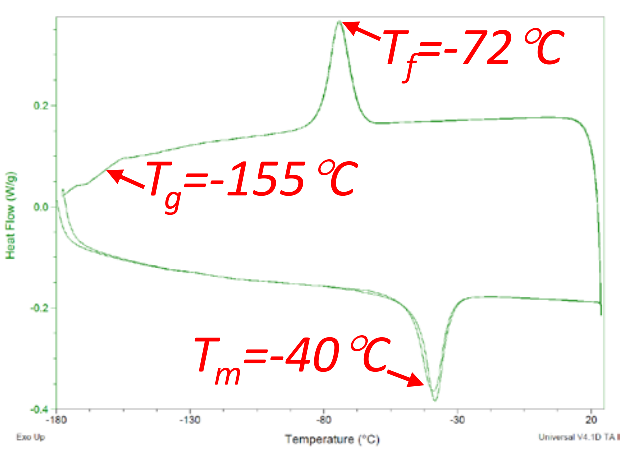
- Glass transitions (T_g aka T_α) may signify likelihood for creep
- The T_g's here are well below the typical operating temperature within fielded modules

- Melt & freeze transitions (T_m & T_f) more commonly correlate to creep in thermoplastics
- The silicones are cross-linked during cure, preventing creep
- T_m hot melts: 75°C (EVA), 81°C (PO), 68°C (PA)

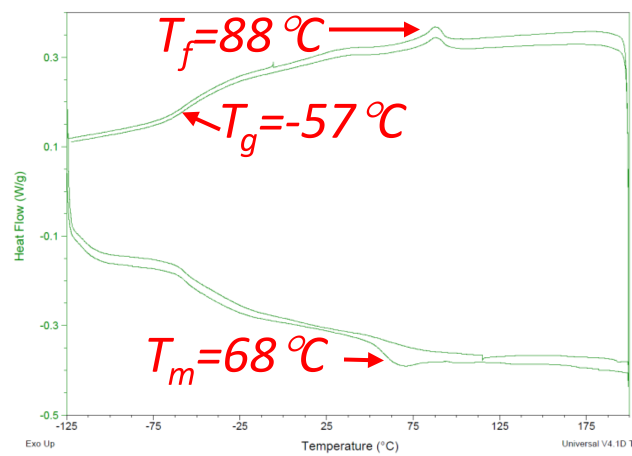
How will the hot melts fare in component tests?



DSC for acrylic foam tape

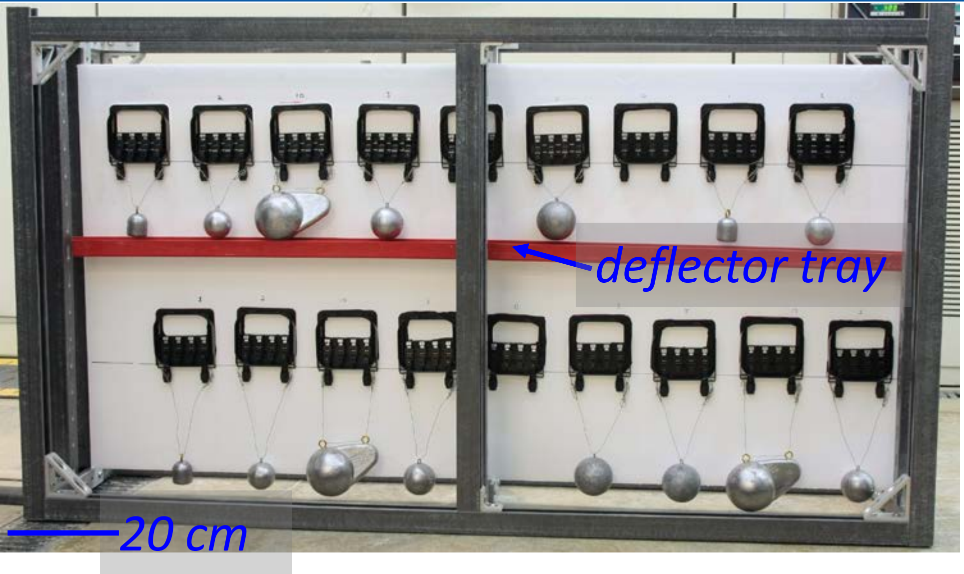


DSC for condensation silicones



DSC for PA hot melt

Two Sets of Discovery Experiments Examine the Adhesives



TF j-box (2 rail) on glass:

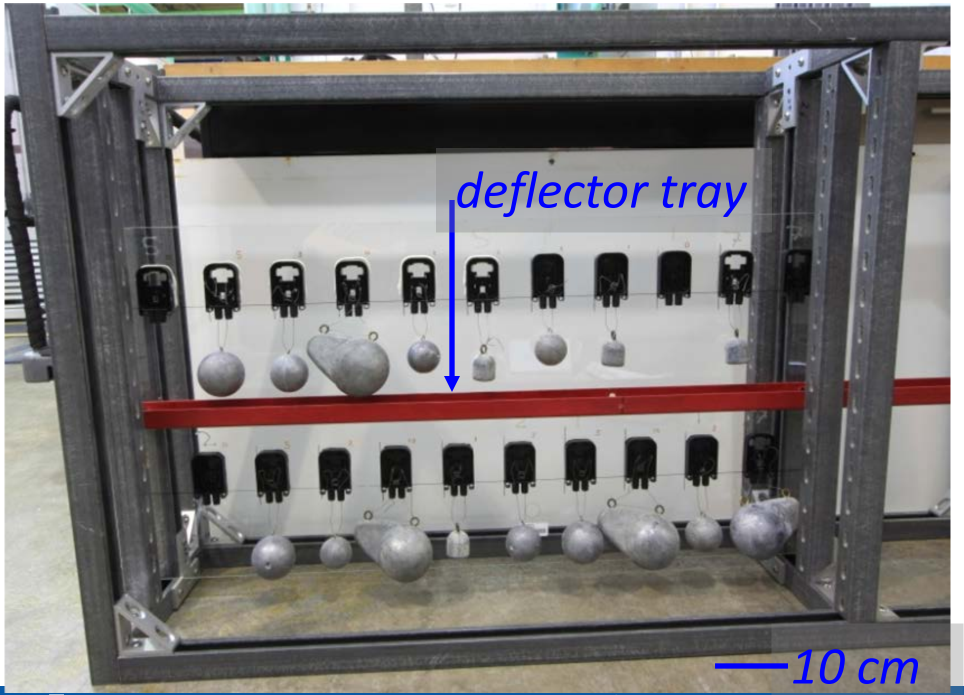
- Pb Weights: 0, 0.5, 0.9, 1.4, 2.3, 4.5 kg
- Adhesives:

acrylic tape, PU tape, acetoxy silicone, alkoxy silicone (Ti), oxime silicone, PO melt, PA melt

- Attached to Sn side of (cleaned) glass
- Primer applied when recommended

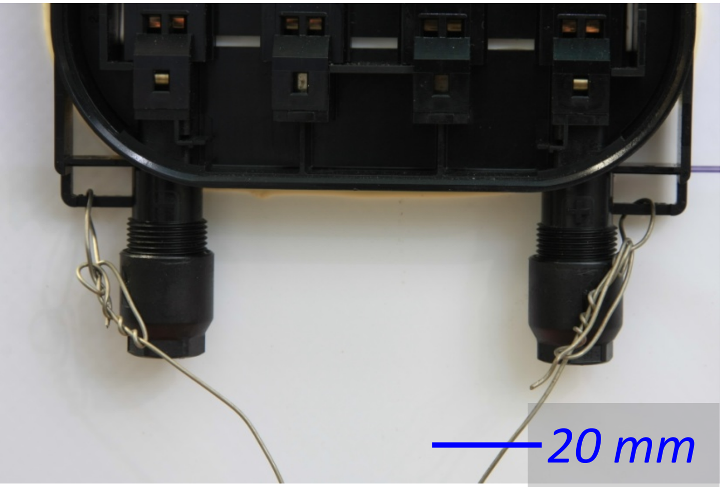
c-Si j-box (4 rail) on PET:

- Pb Weights: 0, 0.5, 0.9, 1.4, 2.3, 4.5 kg
- Adhesives:
  - acrylic tape
  - acrylic tape
  - PE tape
  - acetoxy silicone
  - alkoxy silicone (Ti)
  - oxime silicone
- Primer applied when recommended



The Details of the Weight Attachment

- All weights were attached using 0.81mm ∅ stainless steel wire
- Wire ends secured with knots



<u>c-Si j-box (4 rail) on PET:</u>

- Wire attached to tab features
- Slight torque possible

<u>TF j-box (2 rail) on glass:</u>

- Wire attached thru vias (cable & glands removed)

<u>All:</u>

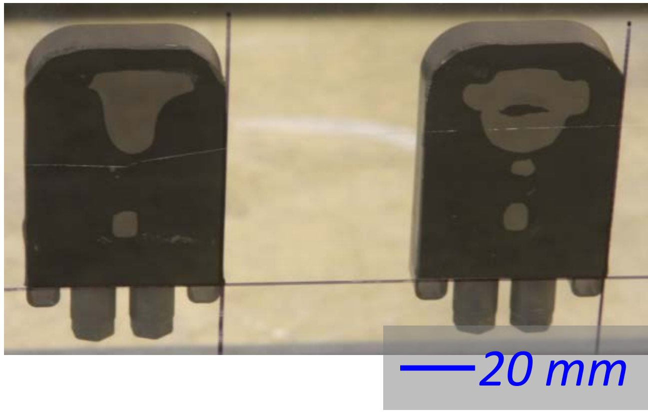
- Predominant shear loading mode
- Boxes left uncovered through the test

Details of the Specimen Attachment

- Easily visualized through substrate for TF specimens

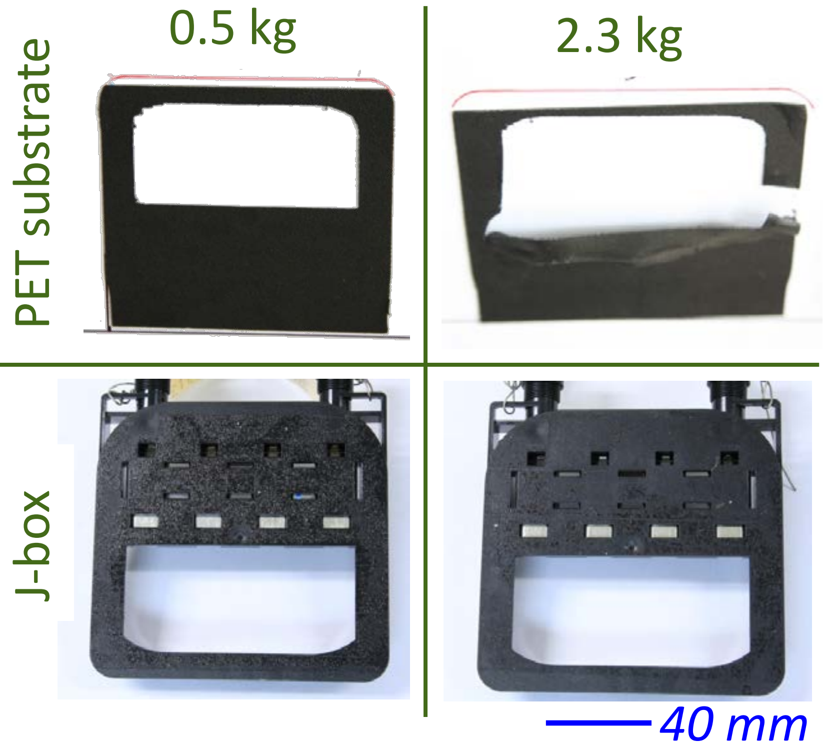
- Silicones adhered by (flatten) bead placed around periphery using “gun”

- Tapes: good wet-out, except @cut-out regions (TF)
- No tape used at cut-outs in c-Si specimens



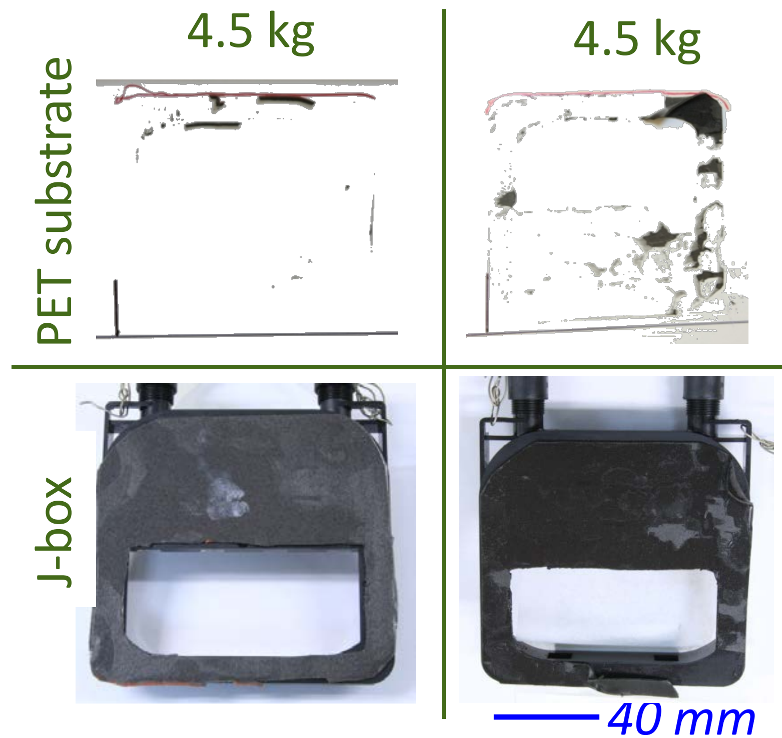
- Melts: adhered by (flatten) bead placed around periphery using heated “gun”
- Original bead for melts smaller than that for silicones

Loss of Adhesion for Tape During the c-Si Test



- all PE tape lost adhesion within 24 hrs
- delamination @ tape/j-box interface
- 2.3, 4.5 kg weights: torn tape (mixed mode failure)
- use system of compatible materials (j-box, adhesive, and substrate)

- acrylic tape lost adhesion 6-7, 7-14 days (4.5 kg weights only)
- delamination @ tape/substrate interface
- loaded exceeding the manufacturer's design guideline



Deformation of Tape During the c-Si Test

- Elongation of acrylic tape observed for 1.4, 2.3 kg weights @ 7-14, 14-21 days

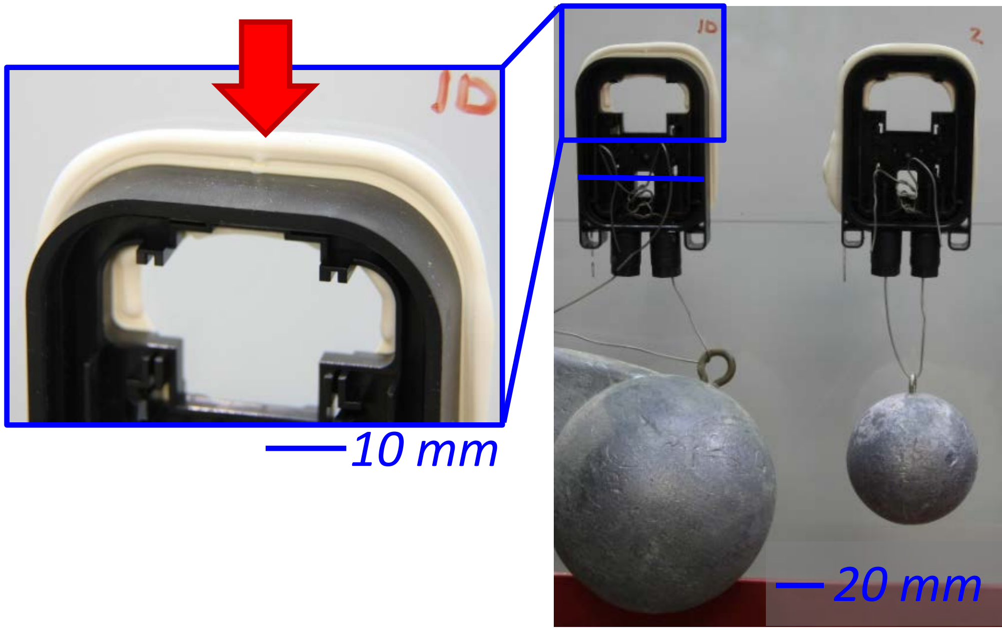
- Remained attached through test (41 days)
- Consistent with intended dissipative behavior: adjustment facilitating mechanical support
- Not observed during TF test for same material (similar load)

- Careful not to stretch tape during application

- Polymeric adhesives: H_2O may plasticize

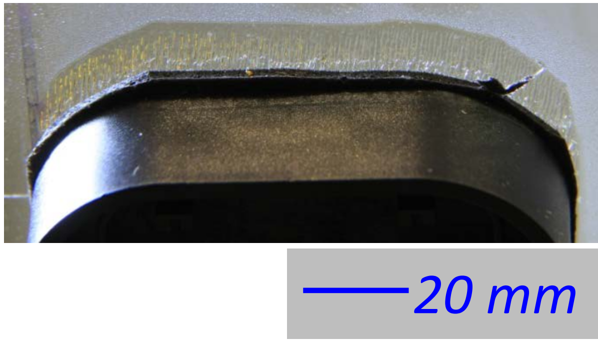
Perceived Deformation of Silicone During the TF Test

- 4.5 kg weighted alkoxy (Ti) silicone appeared displaced @ 5-7 days



- Actually displaced (bumped) during specimen preparation and unchanged through the test
- Condensation silicones require H_2O to cure (CO is dry)
- 21 day cure recommended prior to material tests in dry climates

Loss of Adhesion for Tape During the TF Test



creep of 0.5 kg weighted PU tape at 14 days

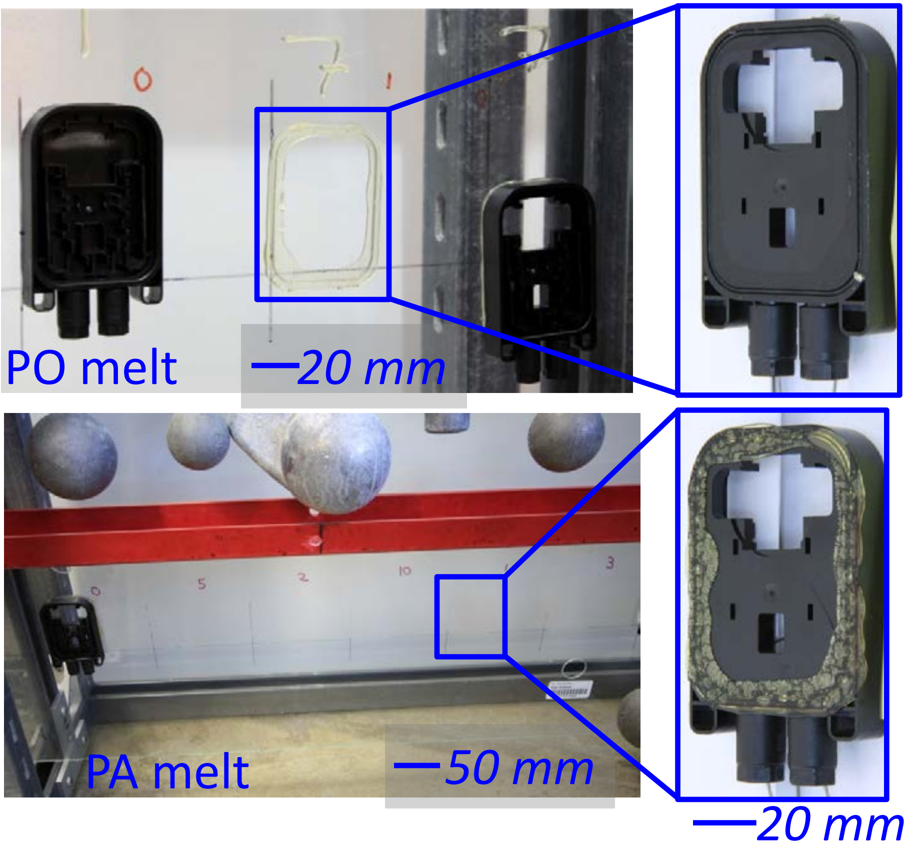
<u>PU tape:</u>

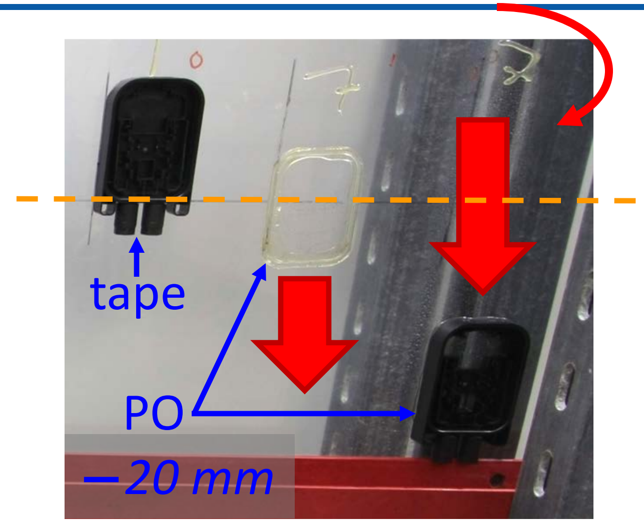
- Weights > 0.5 kg lost adhesion within 24 hours
- Delamination at tape/glass interface (tape remains on j-box)
- 0, 0.5 kg weighted specimen remained attached through test
- *0.5 kg weighted specimen displaced (adhesive/glass) during the test*

<u>acrylic tape:</u>

- Only 2.3, 4.5 kg weighted specimens lost adhesion within 24 hours
- Delamination at tape/j-box interface (tape remains on glass)
- Results as expected from manufacturer's design guideline

Delamination & Creep in Hot Melts During the TF Test





- Delamination of weighted PO & PA melts within 24 hrs
- PO adhered to glass; PA to j-box

- Unweighted PO & PA melts displaced over days, even without the j-box!
- Melt composed lettering rotated through test

- Result consistent with DSC characterization
- Melts identified by material vendor:

  understanding product (field) requirements can be critical! 85°C<105°C

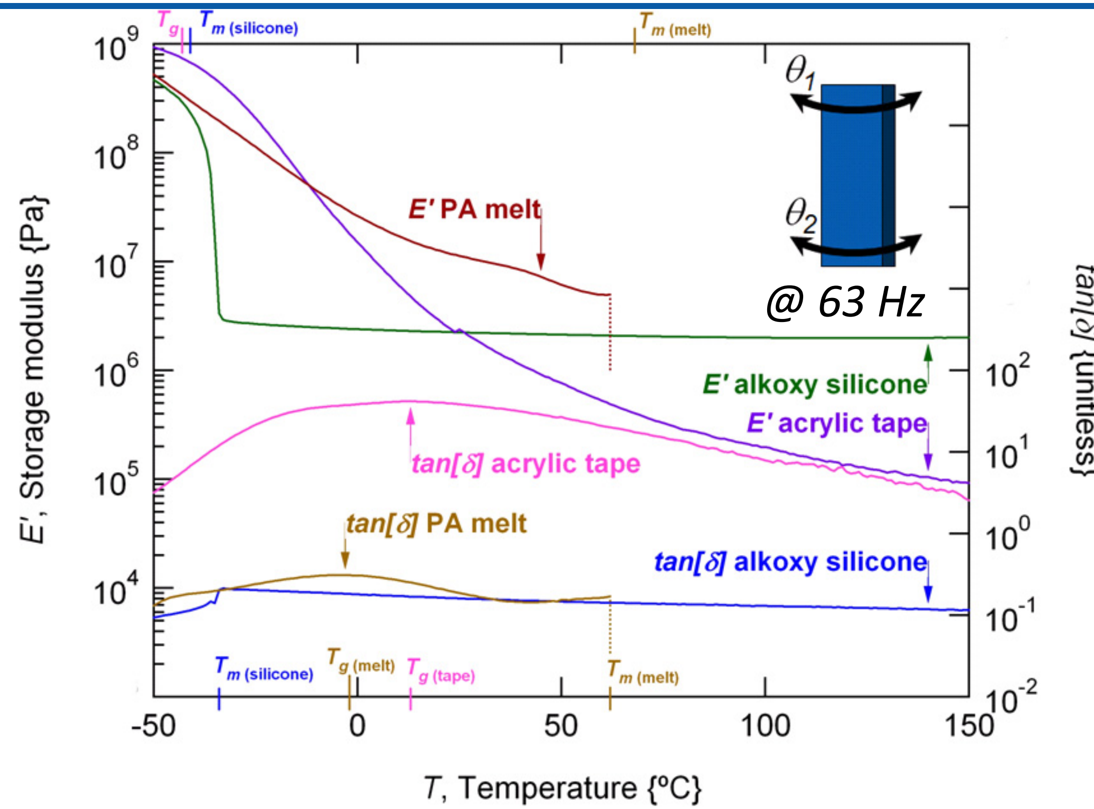
DMA Confirms the Behaviors Observed in the Component-Level Tests

silicones:

- Stable modulus after melt transition @ low temperature
- Would likely creep, if not cross-linked (cured)

tapes:

- Significant (10^4x) softening of modulus with temperature
- Significant mechanical dissipation (tan [δ]) at all *T* (advantagous in vibration or impact-prone environment)
- Some tapes melt @ T>100°C



10's of Hz: order of magnitude for mechanical resonance
K.-A. Weiss et. al., Proc. SPIE, 7412, 2009, 741203.

melts:

- Softening of modulus with glass transition
- More significant softening of modulus (terminates test) with melt transition
- Phase transition confirmed in component-level (TF) test

The Formal Experiment (Future)

Goal: Test the proposed test (indoor vs. field) using a representative set of known good, known incompatible, and intermediate systems

Weights

- 0, 0.5, 1 kg (0, 1, 2 lbs). Consider 4x weight of (2) 1.5m connector cables = 0.7 kg

Adhesives

- 13 examined in the discovery experiments
- Down-selected to 7 (some likely failures, many expected successes)

[acrylic tape, PE tape, PO hot melt, acetoxy cure silicone, oxime cure silicone, alkoxy cure silicone (Ti), alkoxy cure silicone (Ti, high green strength)]

J-boxes

- A c-Si and thin film version have been selected

Substrates

- TPE, PET, THV, glass

Test sites

- Miami (FL), Phoenix (AZ), Golden (CO – outdoors), indoor test chamber

Test orientation

- 45° (shear & tensile) or 0° (vertical: shear only, indoors)

Test duration

- 1 year (outdoors) or 1000 hours (indoors)

Summary

- Proposed modification to qual. test: add weight to j-box during DH
- Discovery experiments to select weights & adhesive systems

- Silicones: allow adequate curing prior to handling
  - cross-linking limits deformation above T_m
- Foam tapes: some incompatible material systems, *e.g.*, PE/j-box
  - adhesion within manufacturer's design guidelines, *e.g.*, acrylic
  - possible feature: significant mechanical dissipation (all)
- Hot melts: delamination & creep observed
  - T_m too low for materials examined (not cross-linked)
  - know the product (field) requirements

- The formal experiment (intended to validate the test) will:
  - distinguish between proposed weights (0.5 or 1 kg)
  - compare indoor and outdoor environments
  - compare adhesive/substrate systems

Acknowledgments

•NREL: Dr. Peter Hacke, Dr. Michael Kempe, Dr. Heidi Pilath, Ed Gelak, Kent Terwilliger, David Trudell

NATIONAL RENEWABLE ENERGY LABORATORY

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Pending manuscript: “Initial Examination of a Junction-Box Adhesion Test for Use in Module Qualification”, Proc. SPIE 2012.

A Comparison of the DMA Results at Different Test Rates

- 10’s of Hz: mechanical resonance vs. 1’s of mHz: thermal time constant
  - K.-A. Weiss et. al., Proc. SPIE, 7412, 2009, 741203.
  - D.C. Miller et. al., Proc. IEEE PVSC, 2010, 262-268.
- T_m for PA is more obvious from the *tan[δ]*
- The melt temperatures are not strongly strain rate dependent
- T_g reduced with strain rate for PA melt, more so for acrylic tape
- The tape is less dissipative at low strain rates (reduced T_g, reduced area of *tan[δ]* envelope)